



REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	MARK T.	01-06-15

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

APPROVALS

PCB DES. KIM T.

APP ENG. MARK T.

SCALE = NONE



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TITLE: TOP ASSEMBLY DRAWING

FMC COMMUNICATION INTERFACE

SIZE N/A	IC NO. DEMO CIRCUIT 2159A	REV. 2
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FILENAME: DC2159A-2.PCB

SHT 1 OF 2